

AMENDMENT TO THE SPECIFICATION

Please amend the Abstract as follows:

~~It provides In the soldering method, metal-powder-contained flux is disposed between bumps and circuit electrodes when electronic parts are mounted by soldering, the metal powder comprises comprising a core metal formed of metal such as tin and zinc and a surface metal covering surfaces of the core metal formed of noble metal such as gold and silver. Accordingly, metal powder will not remain as residue that is liable to cause migration after the reflow process, and it is possible to assure both soldering effect and insulation effect.~~